

Amendments to the specification:

Please replace the title and paragraph 1 on page 1 of the specification with the following revised title and paragraph:

~~ELECTRONIC PACKAGE WITH FILLED BLIND VIAS~~

METHOD OF FORMING FILLED BLIND VIAS

BACKGROUND OF THE INVENTION

CROSS REFERENCE TO RELATED APPLICATIONS

This application is a divisional of application Serial No. 10/263,909, filed October 3, 2002, Now Publication No. US 2004/0065960 A1.